RELIABILITY REPORT

FOR

**MAX1099xEAE**

PLASTIC ENCAPSULATED DEVICES

April 14, 2003

# MAXIM INTEGRATED PRODUCTS

120 SAN GABRIEL DR.

SUNNYVALE, CA 94086

Written by

Jim Pedicord
Quality Assurance
Reliability Lab Manager

Reviewed by

Bryan J. Preeshl
Quality Assurance
Executive Director

## Conclusion

The MAX1099 successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

## Table of Contents



## I. Device Description

### A. General

The MAX1099 implementa both local and remote temperature sensing with 10-bit resolution, using +5V and +3V supply voltages, respectively. Accuracy is ±1°C from 0°C to +70°C, with no calibration needed. The device featurea an algorithmic switched-capacitor analog-to-digital converter (ADC), on-chip clock, and 3-wire serial interface compatible with SPI™, QSPI™, and MICROWIRE™.

The MAX1099 also performa fully differential voltage measurements with 10-bit resolution and separate track-and-hold (T/N) for positive and negative inputs. The device accepta versatile input modes consisting of two 3-channel signal pairs, five 1-channel signals relative to a floating common, or $V_{DD}$/4 relative to ground. An external reference may be used for more accurate voltage measurements.

Typical power consumption is only 1.3mW. A shutdown mode and two standby modes provide multiple strategies for prolonging battery life in portable applications that require limited sampling throughput.The MAX1099 ia available in 16-pin SSOP packages.

### B. Absolute Maximum Ratings

| Item | Rating |
|---|---|
| VDD to GND | -0.3V to +6V |
| SHO to GND | -0.3V to (VDD +0.3V) |
| Analog Inputs to GND (AIN0–AIN5, REF) | -0.3V to (VDD +0.3V) |
| Digital Inputs to GND (DIN, SCLK, CS) | -0.3V to (VDD +0.3V) |
| Digital Outputs to GND (DOUT, SSTRB) | -0.3V to (VDD +0.3V) |
| Digital Output Sink Current | 25mA |
| Maximum Current into Any Pin | 50mA |
| Operating Temperature Range | -40°C to +85°C |
| Junction Temperature | +150°C |
| Storage Temperature Range | -65°C to +150°C |
| Lead Temperature (soldering, 10s) | +300°C |
| Continuous Power Dissipation (TA = +70°C) | |
| 16-Pin SSOP | 667mW |
| Derates above +70°C | |
| 16-Pin SSOP | 8.00mW/°C |

## II. Manufacturing Information

| | |
|---|---|
| A. Description/Function: | 10-Bit Serial-Output Temperature Sensors with 5-Channel ADC |
| B. Process: | S12 (Standard 1.2 micron silicon gate CMOS) |
| C. Number of Device Transistors: | 13,669 |
| D. Fabrication Location: | California or Oregon, USA |
| E. Assembly Location: | Philippines |
| F. Date of Initial Production: | March, 2000 |

## III. Packaging Information

| | |
|---|---|
| A. Package Type: | **16-Pin SSOP** |
| B. Lead Frame: | Copper |
| C. Lead Finish: | Solder Plate |
| D. Die Attach: | Silver-filled Epoxy |
| E. Bondwire: | Gold (1.0 mil dia.) |
| F. Mold Material: | Epoxy with silica filler |
| G. Assembly Diagram: | # 05-0101-0503 |
| H. Flammability Rating: | Class UL94-V0 |
| I. Classification of Moisture Sensitivity per JEDEC standard JESD22-112: | Level 1 |

## IV. Die Information

| | |
|---|---|
| A. Dimensions: | 144 x 170 mils |
| B. Passivation: | $Si_3N_4/SiO_2$ (Silicon nitride/ Silicon dioxide) |
| C. Interconnect: | Aluminum/Si (Si = 1%) |
| D. Backside Metallization: | None |
| E. Minimum Metal Width: | 1.2 microns (as drawn) |
| F. Minimum Metal Spacing: | 1.2 microns (as drawn) |
| G. Bondpad Dimensions: | 5 mil. Sq. |
| H. Isolation Dielectric: | $SiO_2$ |
| I. Die Separation Method: | Wafer Saw |

## V. Quality Assurance Information

A. Quality Assurance Contacts: Jim Pedicord (Manager, Rel Operations)
Bryan Preeshl (Executive Director**)**
Kenneth Huening (Vice President)

B. Outgoing Inspection Level: 0.1% for all electrical parameters guaranteed by the Datasheet.
0.1% For all Visual Defects.

C. Observed Outgoing Defect Rate: < 50 ppm

D. Sampling Plan: Mil-Std-105D

## VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135°C biased (static) life test are shown in **Table 1**. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{MTTF} = \frac{1.83}{192 \times 4389 \times 46 \times 2}$$ (Chi square value for MTTF upper limit)

Temperature Acceleration factor assuming an activation energy of 0.8eV

$\lambda = 23.61 \times 10^{-9}$

$\lambda = 23.61$ F.I.T. (60% confidence level @ 25°C)

This low failure rate represents data collected from Maxim's reliability monitor program. In addition to routine production Burn-In, Maxim pulls a sample from every fabrication process three times per week and subjects it to an extended Burn-In prior to shipment to ensure its reliability. The reliability control level for each lot to be shipped as standard product is 59 F.I.T. at a 60% confidence level, which equates to 3 failures in an 80 piece sample. Maxim performs failure analysis on any lot that exceeds this reliability control level. Attached Burn-In Schematic (Spec. # 06-5477) shows the static Burn-In circuit. Maxim also performs quarterly 1000 hour life test monitors. This data is published in the Product Reliability Report (**RR-1M**).

B. Moisture Resistance Tests

Maxim pulls pressure pot samples from every assembly process three times per week. Each lot sample must meet an LTPD = 20 or less before shipment as standard product. Additionally, the industry standard 85°C/85%RH testing is done per generic device/package family once a quarter.

C. E.S.D. and Latch-Up Testing

The AD97 die type has been found to have all pins able to withstand a transient pulse of ±2000V, per Mil-Std-883 Method 3015 (reference attached ESD Test Circuit). Latch-Up testing has shown that this device withstands a current of ±250mA.

**Table 1**
Reliability Evaluation Test Results

**MAX1099xEAE**

| TEST ITEM | TEST CONDITION | FAILURE IDENTIFICATION | PACKAGE | SAMPLE SIZE | NUMBER OF FAILURES |
|---|---|---|---|---|---|
| **Static Life Test** (Note 1) | | | | | |
| | Ta = 135°C<br>Biased<br>Time = 192 hrs. | DC Parameters<br>& functionality | | 46 | 0 |
| **Moisture Testing** (Note 2) | | | | | |
| Pressure Pot | Ta = 121°C<br>P = 15 psi.<br>RH= 100%<br>Time = 168hrs. | DC Parameters<br>& functionality | SSOP | 77 | 0 |
| 85/85 | Ta = 85°C<br>RH = 85%<br>Biased<br>Time = 1000hrs. | DC Parameters<br>& functionality | | 77 | 0 |
| **Mechanical Stress** (Note 2) | | | | | |
| Temperature Cycle | -65°C/150°C<br>1000 Cycles<br>Method 1010 | DC Parameters | | 77 | 0 |

Note 1: Life Test Data may represent plastic DIP qualification lots.
Note 2: Generic Package/Process data

**Attachment #1**

TABLE II. Pin combination to be tested. 1/ 2/

| | Terminal A (Each pin individually connected to terminal A with the other floating) | Terminal B (The common combination of all like-named pins connected to terminal B) |
|---|---|---|
| 1. | All pins except $V_{PS1}$ 3/ | All $V_{PS1}$ pins |
| 2. | All input and output pins | All other input-output pins |

1/ Table II is restated in narrative form in 3.4 below.
2/ No connects are not to be tested.
3/ Repeat pin combination I for each named Power supply and for ground

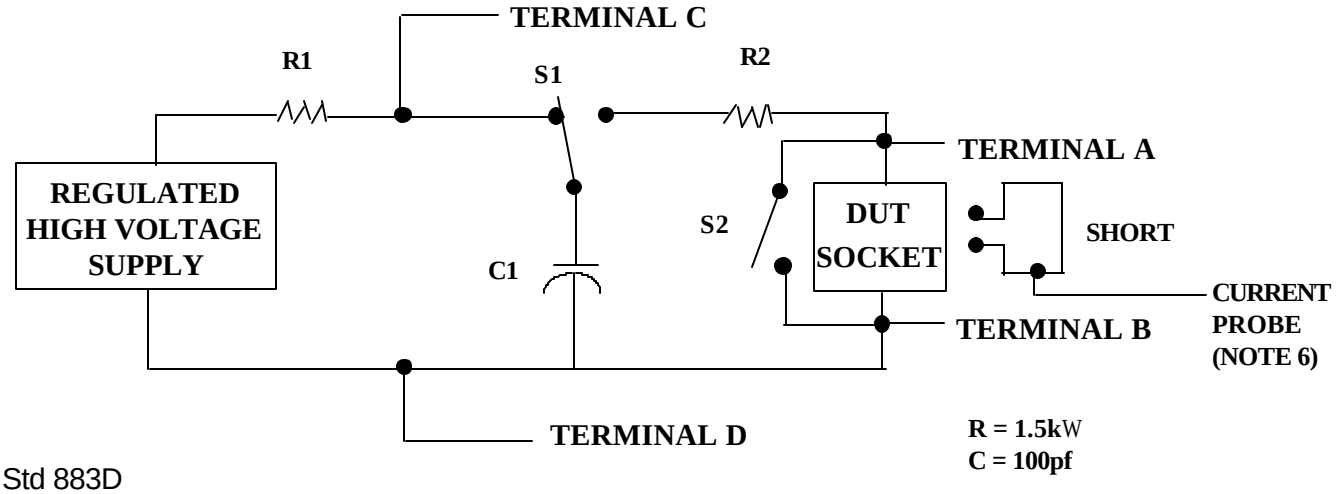
(e.g., where $V_{PS1}$ is $V_{DD}$, $V_{CC}$, $V_{SS}$, $V_{BB}$, GND, $+V_S$, $-V_S$, $V_{REF}$, etc).

3.4 Pin combinations to be tested.

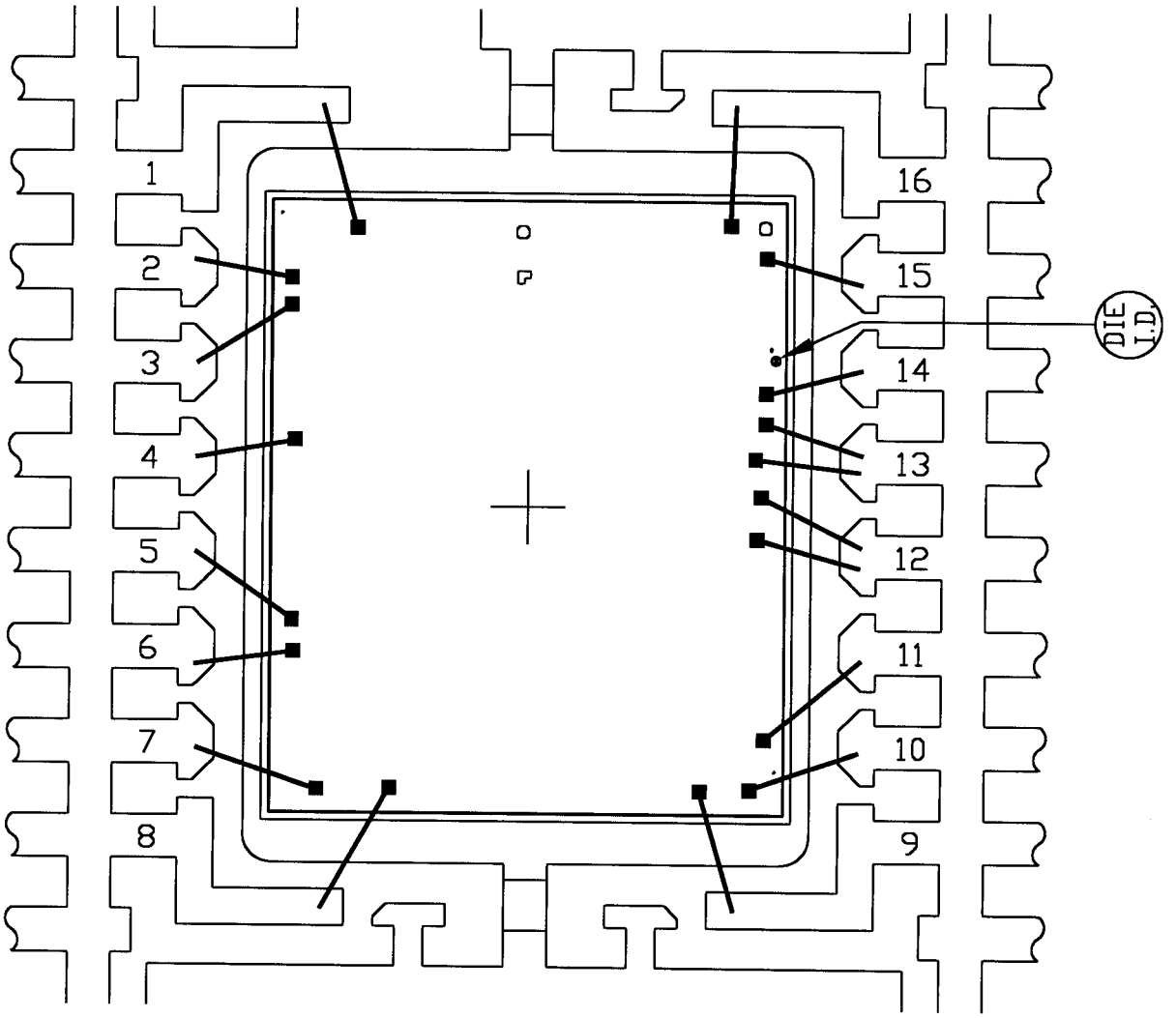
a. Each pin individually connected to terminal A with respect to the device ground pin(s) connected to terminal B. All pins except the one being tested and the ground pin(s) shall be open.

b. Each pin individually connected to terminal A with respect to each different set of a combination of all named power supply pins (e.g., $V_{SS1}$, or $V_{SS2}$ or $V_{SS3}$ or $V_{CC1}$, or $V_{CC2}$) connected to terminal B. All pins except the one being tested and the power supply pin or set of pins shall be open.

c. Each input and each output individually connected to terminal A with respect to a combination of all the other input and output pins connected to terminal B. All pins except the input or output pin being tested and the combination of all the other input and output pins shall be open.

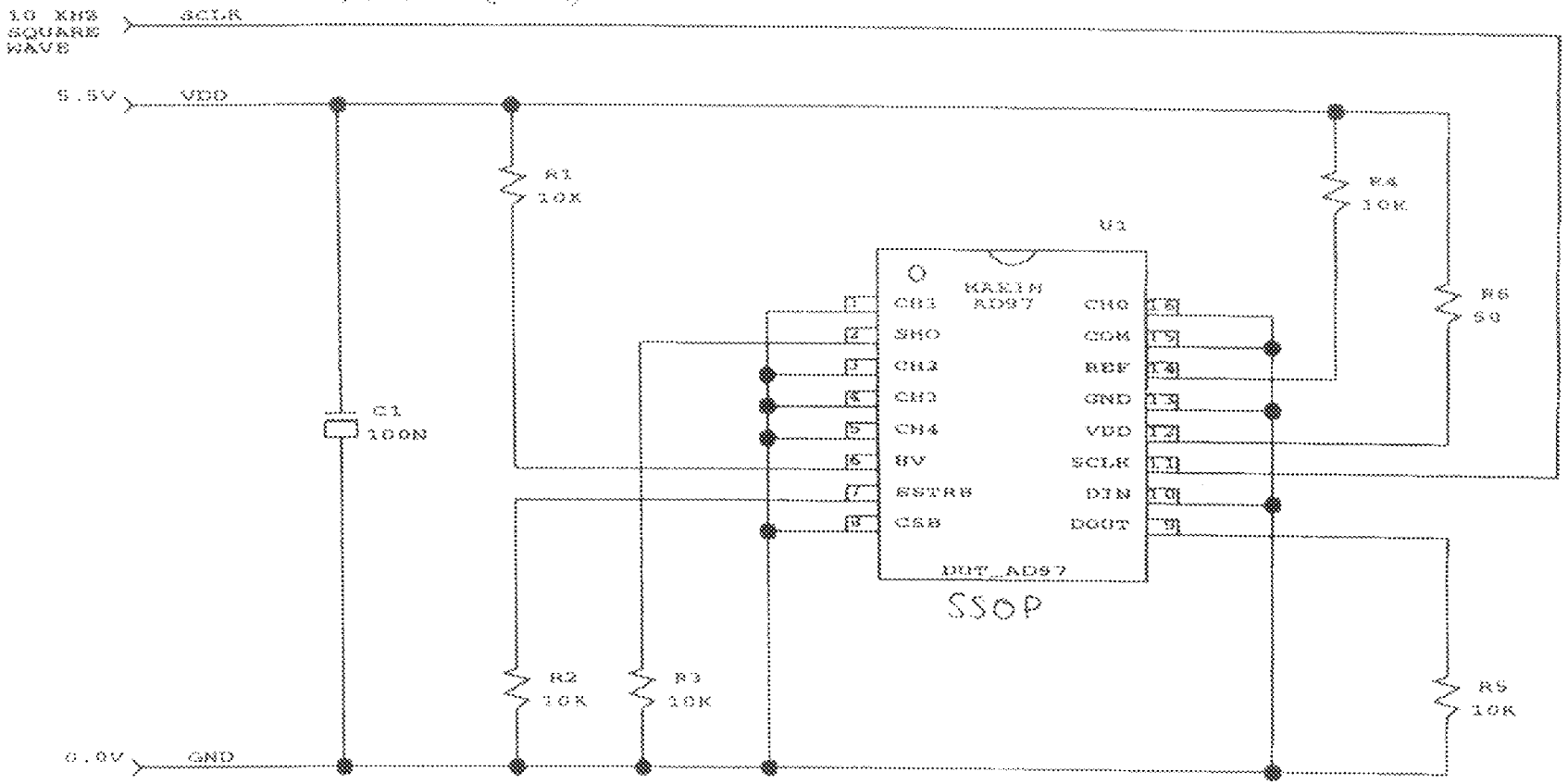



Mil Std 883D
Method 3015.7
Notice 8




| PKG.CODE: A16-3 | | APPROVALS | DATE | MAXIM |
|---|---|---|---|---|
| CAV./PAD SIZE: 154x193 | PKG. DESIGN | | | BUILDSHEET NUMBER: 05-0101-0503 / REV.: A |

500uA (AVG)
2mA (MAX)




MAX1098/99 MAX1298/99

| | | | | | |
|---|---|---|---|---|---|
| MAXIM CONFIDENTIAL | CREATED: 00/00/00 | BY: - | ENG1: | ENG2: - | |
| | LAST SAVED: 6-27-1999_10:38 | | SIZE A | REVISION A 00/00/00 | SPEC NO. 06-5477 |
| AD97 BURN-IN BOARD | PROJECT: - | | | | |
| | DESC.: - | | FILE: bib | SHEET 1 OF 1 | |